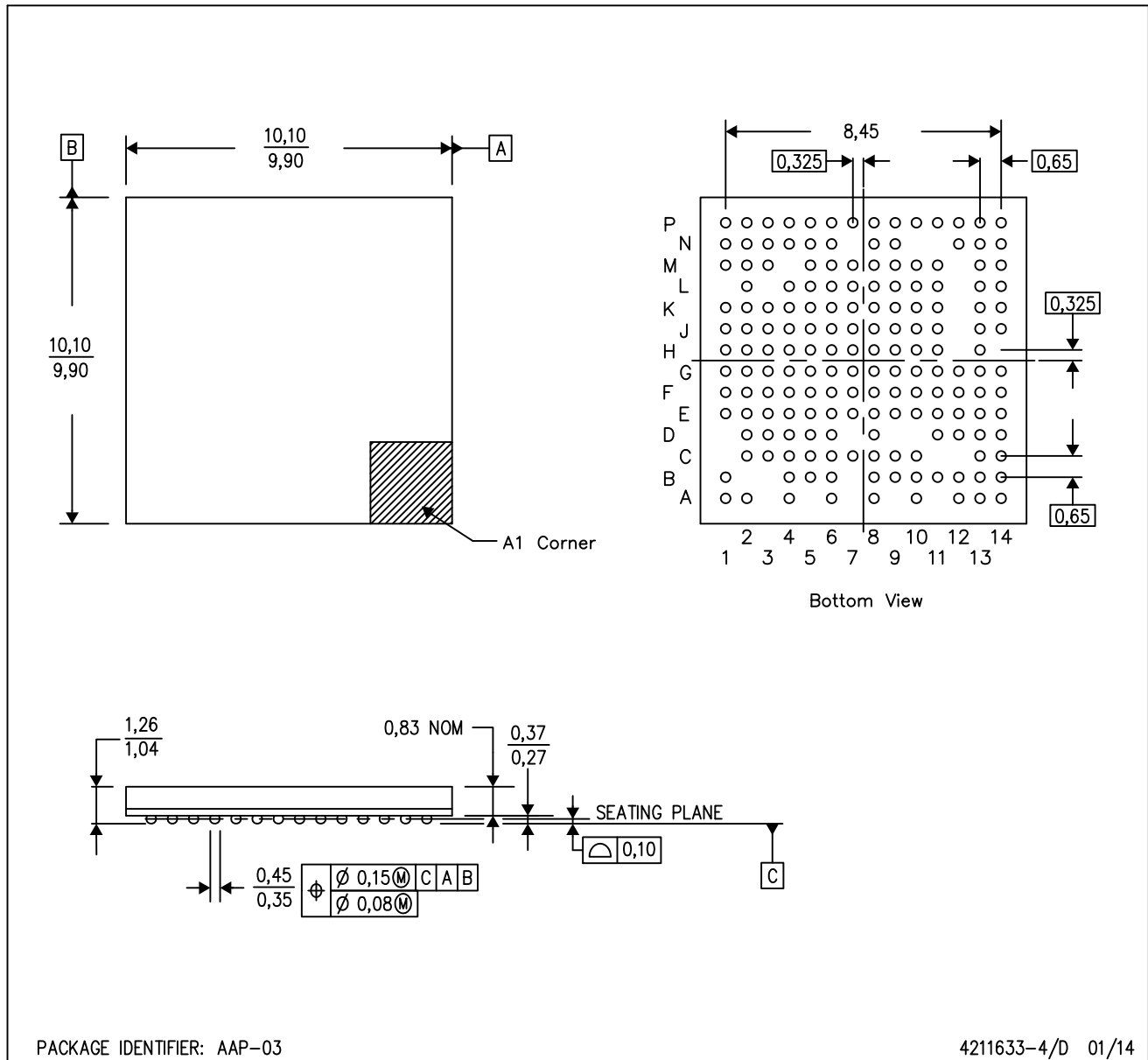


AAP (S-FCBGA-N169)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y1.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Flip chip application only.
 - D. Pb-free bump and solder ball.

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